

TOPSELLER

Fully-Automatic
BG Tape Peeler

RAD-3010F/12



- ☾: 180-degree peeling technique
- ⊞ Prevents wafer circuit damage
- ⦿ Closed-loop UV-illuminance control



LINTEC Corporation

BENEFITS

180-degree peeling technique

Maintaining an ideal peeling-angle of 180 degrees during delamination of the BG tape minimizes stress on fragile and thin wafers.



Prevents wafer circuit damage

By thermocompression-bonding a heat-seal peeling-tape to the BG tape within 3mm of the wafer's periphery, the risk of damage to the wafer surface is reduced to an absolute minimum.



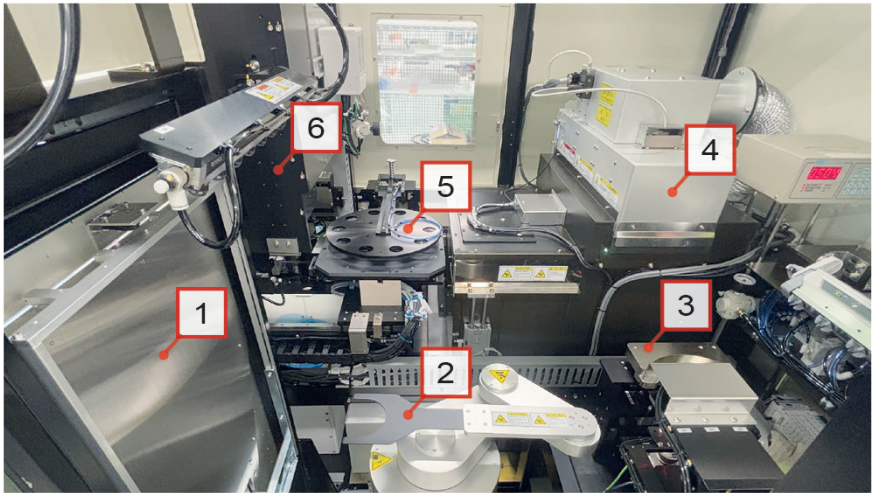
Closed-loop UV-illuminance control

A built-in control-sensor guarantees constant UV-illuminance. The selection of an individually programmable irradiation-speed within a defined recipe ensures stable UV conditions to achieve flawless peeling results.



**Minimal stress
BG tape peeling
technology**

MACHINE INSIDE VIEW

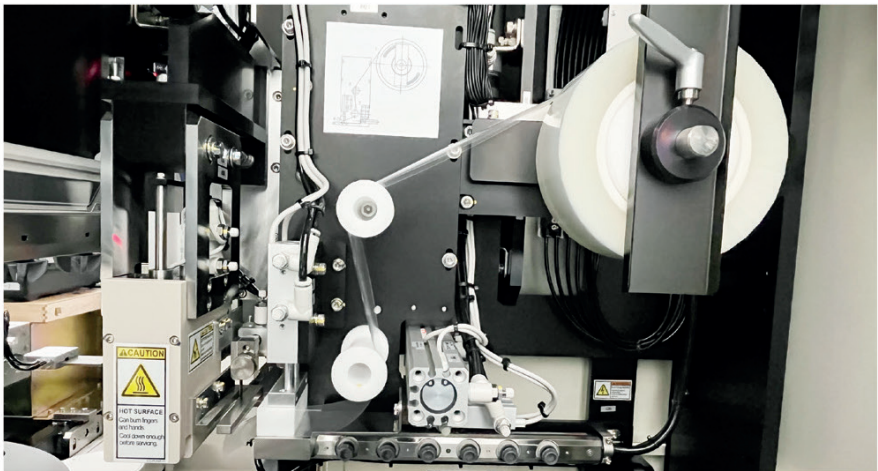


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|----------|--------------------------------|----------|---------------------|
| 1 | Loading unit | 2 | Robot transfer-arm |
| 3 | Alignment unit | 4 | UV-irradiation unit |
| 5 | BG tape peeling unit | | |
| 6 | Heat-seal tape attachment unit | | |

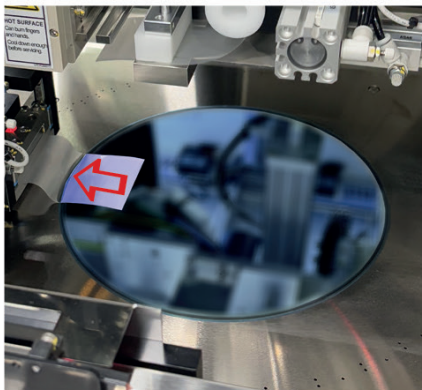
SPECIFICATION

Weight	1,100 kg
Wafer size	300mm, 200mm Optional: 150mm
Wafer cassette	Φ300mm: FOSB, FOUP (Index pitch=10mm) Φ200mm: Open (Index pitch=6.35mm)
Peeling tape	Heat seal tape
UPH	65 wafers/hour* *Standard machine specification. Φ200mm, mirror-polished wafer with 725μm thickness

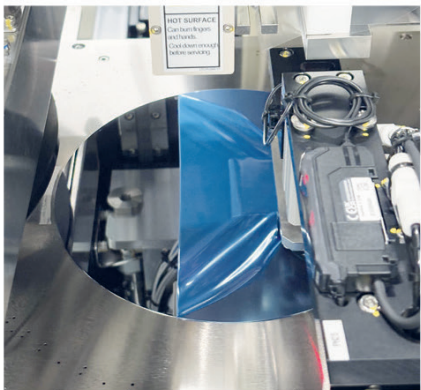
PEELING PROCESS



Heat-seal tape attachment unit



Heat-seal tape attachment



180-degree BG tape peeling

Following alignment and UV-irradiation, the wafer is placed on the full-contact peeling table by the robot transfer-arm.

Afterwards, the heat-seal peeling-tape is thermocompression-bonded to the BG tape within 3mm of the wafer's periphery and then peeled in an ideal 180 degree angle. This approach greatly reduces the occurrence of adhesive residues, as well as damage to the wafer surface. The circuit side is often damaged during the application of standard peeling tape, which is attached to the BG-tape using pressure across the wafer surface. LINTEC's peeling method minimizes stress to the wafer and allows for processing of thin wafers down to 200µm for 200mm wafers and 300µm for 300mm wafers.



STANDARD

- Handling of 300mm and 200mm wafers
- 180-degree peeling technique minimizes stress to the wafer while the tape is peeled
- Built-in UV-irradiation unit
- Single load port for FOUP/FOSB or cassette
- Anti-ESD specification:
±100V or less within 10sec after the end of operation
- Heatable peeling table, up to max. 80°C



OPTIONS

- Handling of 150mm wafers
- Double load port for FOUP / FOSB or cassette
- Additional ionizer specification
- HEPA filter clean-air spec
- Warped wafer handling specification
- Multi-functional handy barcode-reader
- Host communication function (SECS/GEM)
- OHT capability
- Wafer table cleaning function



Adwill

Tape x Equipment

Contact us.
We look forward
to meeting you!



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